# N-Channel 120 V (D-S) MOSFET

PRODUCT SUMMARY								
V <sub>DS</sub> (V)	$R_{DS(on)}(m\Omega)(Typ.)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)					
120	5.6 at V <sub>GS</sub> = 10 V	87	32 nC					

#### **FEATURES**

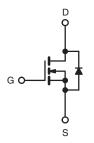
- DT-SGT Power MOSFET
- · Low On-resistance
- Excellent FOM(Figure of Merit)
- 100% UIS and Rg Tested

#### **APPLICATIONS**

- · Synchronous Rectification in SMPS
- DC/DC in Telecoms and Inductrial
- · Hard Switching and High Speed Circuit

#### **DFN5X6-8L Pin Configuration**





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage	V <sub>DS</sub>	120	V		
Gate-Source Voltage	V <sub>GS</sub>	± 20	V		
Continuous Prais Current /T 450°C\ 3	T <sub>C</sub> = 25 °C	I <sub>D</sub>	87	A	
Continuous Drain Current (T <sub>J</sub> = 150°C) <sup>a</sup>	T <sub>C</sub> = 100 °C		55		
Pulsed Drain Current <sup>b</sup>	I <sub>DM</sub>	349	A		
Single Pulse Avalanche Current	I <sub>AS</sub>	47			
Single Avalanche Energy	E <sub>AS</sub>	336	mJ		
Maximum Power Dissipation <sup>c</sup>	T <sub>C</sub> = 25 °C	P <sub>D</sub>	96	W	
iviaximum Fower Dissipation	T <sub>C</sub> = 100 °C	T CD	38	VV	
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C		

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	LIMIT	UNIT		
Junction-to-Ambient (PCB Mount) <sup>d</sup>	$R_{thJA}$	43	°C/W		
Junction-to-Case (Drain)	R <sub>thJC</sub>	1.3	]		

- a. Calculated continuous current based on maximum allowablejunction temperature.
- b. Repetitive rating; pulse width limited by max. junction temperature.
- c. Pd is based on max. junction temperature, using junction-case thermal resistance.
- d. The value of R<sub>0JA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper,in a still air environment with Ta=25 °C.





PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static	_					
Drain-Source Breakdown Voltage	V <sub>DS</sub>			-	-	V
Gate Threshold Voltage	V <sub>GS(th)</sub>			-	4.0	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
Zoro Goto Voltago Drain Current		V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V	-	-	1 ,,,	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 96 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	100		100	μA
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	87	-	-	Α
Drain-Source On-State Resistance <sup>a</sup>			-	5.6	6.7	mΩ
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	$V_{DS} = 5 \text{ V}, I_{D} = 20 \text{ A}$	-	36	-	S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>		-	2119	-	pF
Output Capacitance	Coss	$V_{GS} = 0 \text{ V}, V_{DS} = 60 \text{ V}, f = 1 \text{ MHz}$	-	928	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	17	-	
Total Gate Charge <sup>c</sup>	Qg		-	32	-	nC
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 60 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	8.5	-	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$		-	6.6	-	
Gate Resistance	$R_g$	f = 1 MHz	-	1.1	-	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>		-	6.8	-	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 60 \text{ V}, \text{ R}_{GEN} = 3 \Omega, \text{ I}_{D} = 20 \text{ A},$	-	8.7	-	no
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	V <sub>G</sub> S = 10 V	-	18	-	ns ns
Fall Time <sup>c</sup>	t <sub>f</sub>		-	9	-	
Drain-Source Body Diode Ratings and	Characterist	ics b (T <sub>C</sub> = 25 °C)				
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	-	-	87	Α
Pulsed Current	I <sub>SM</sub>				349	Α
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 2 A, V <sub>GS</sub> = 0 V	-	0.7	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	1 00 4 45/45 - 400 4/22	-	60	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/μs	-	123	-	nC

#### Notes

- a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those in dicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



### TYPICAL CHARACTERISTICS (25°C unless otherwise noted)

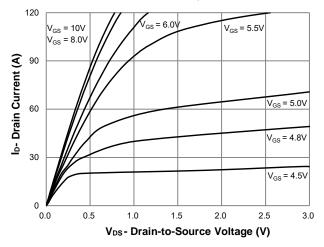


Figure 1: Output Characteristics

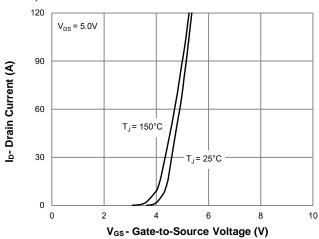


Figure 2: Transfer Characteristics

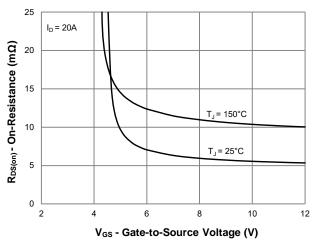
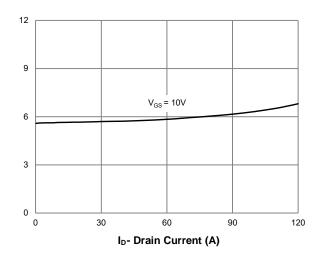


Figure 3: On-Resistance vs. Gate-Source Voltage



R<sub>DS(on)</sub> - On-Resistance (mΩ)

Figure 4: On-Resistance vs. Gate-Source Voltage

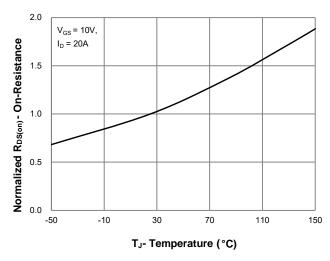


Figure 5: On-Resistance vs. Junction Temperature

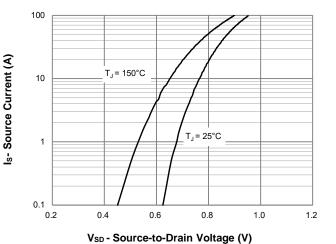


Figure 6: Source-Drain Diode Forward Voltage



#### TYPICAL CHARACTERISTICS (25°C unless otherwise noted)

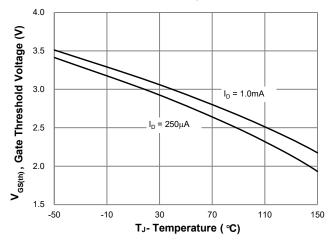


Figure 7: Gate Threshold Variation vs. Junction Temperature

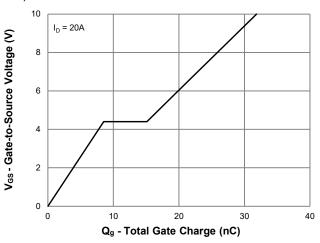


Figure 8: Gate Charge Characteristics

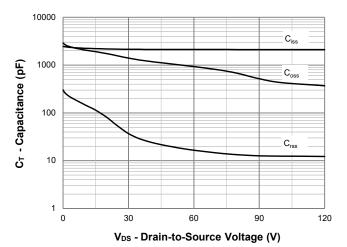


Figure 9: Capacitance Characteristics

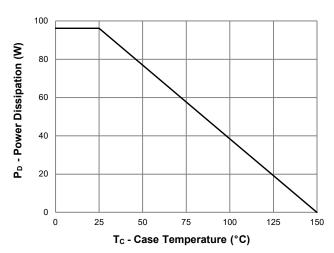


Figure 10: Power Derating

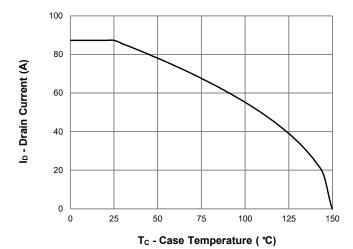
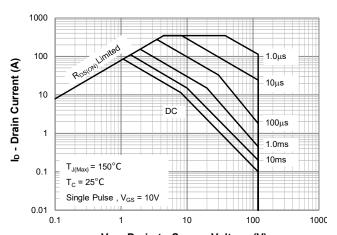


Figure 11: Current Derating



V<sub>DS</sub> - Drain-to-Source Voltage (V)

Figure 12: Safe Operating Area



### TYPICAL CHARACTERISTICS (25°C unless otherwise noted)

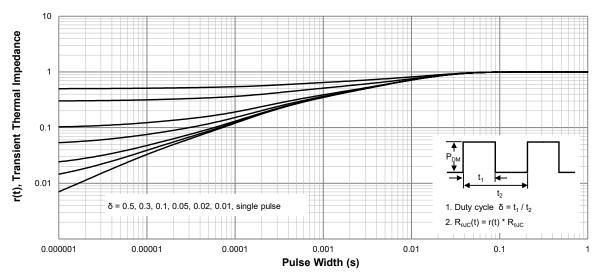
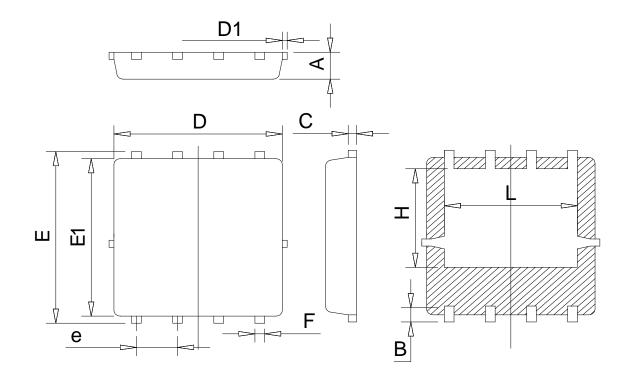


Figure 13: Normalized Maximum Transient Thermal Impedance



## DFN5X6-8L PACKAGE OUTLINE



## **COMMON DIMENSIONS** (UNITS OF MEASURE=MILLIMETER)

Symbol	Min	Тур	Max
Α	0.78	0.95	1.12
В	0.45	0.58	0.78
С	0.18	0.254	0.36
D	4.70	5.20	5.45
D1			0.18
Е	5.85	6.05	6.25
E1	5.38	5.55	5.98
е	1.15	1.27	1.40
F	0.18	0.30	0.52
Н	3.25	3.47	3.70
L	3.75	4.00	4.25





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